

### Features

- **Buffered Inputs**
- **Typical Propagation Delay**
  - 4.3ns at  $V_{CC} = 5V$ ,  $T_A = 25^{\circ}C$ ,  $C_L = 50pF$
- **Exceeds 2kV ESD Protection MIL-STD-883, Method 3015**
- **SCR-Latchup-Resistant CMOS Process and Circuit Design**
- **Speed of Bipolar FAST™/AS/S with Significantly Reduced Power Consumption**
- **Balanced Propagation Delays**
- **AC Types Feature 1.5V to 5.5V Operation and Balanced Noise Immunity at 30% of the Supply**
- **±24mA Output Drive Current**
  - Fanout to 15 FAST™ ICs
  - Drives 50Ω Transmission Lines

### Description

The 'AC08 and 'ACT08 are quad 2-input AND gates that utilize Advanced CMOS Logic technology.

### Ordering Information

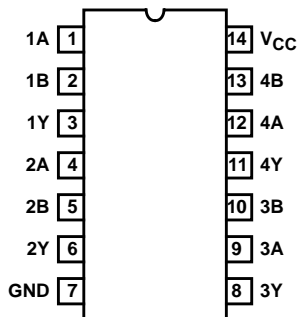
PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54AC08F3A	-55 to 125	14 Ld CERDIP
CD74AC08E	-55 to 125	14 Ld PDIP
CD74AC08M	-55 to 125	14 Ld SOIC
CD54ACT08F3A	-55 to 125	14 Ld CERDIP
CD74ACT08M	-55 to 125	14 Ld SOIC

#### NOTES:

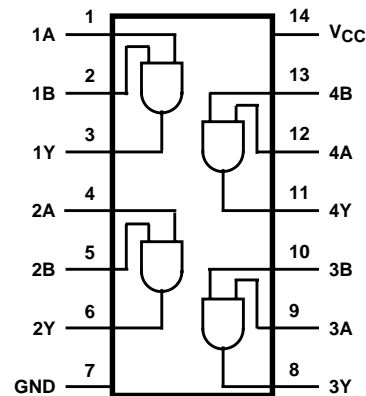
1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
2. Wafer and die for this part number is available which meets all electrical specifications. Please contact your TI local sales office or customer service for ordering information.

### Pinout

CD54AC08, CD54ACT08  
(CERDIP)  
CD74AC08, CD74ACT08  
(PDIP, SOIC)  
TOP VIEW



### Functional Diagram



TRUTH TABLE

INPUTS		OUTPUTS
nA	nB	nY
L	L	L
H	L	L
L	H	L
H	H	H

# CD54/74AC08, CD54/74ACT08

## Absolute Maximum Ratings

DC Supply Voltage, $V_{CC}$ .....	-0.5V to 6V
DC Input Diode Current, $I_{IK}$	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Output Diode Current, $I_{OK}$	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ .....	$\pm 50mA$
DC Output Source or Sink Current per Output Pin, $I_O$	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ .....	$\pm 50mA$
DC $V_{CC}$ or Ground Current, $I_{CC}$ or $I_{GND}$ (Note 3) .....	$\pm 100mA$

## Thermal Information

Thermal Resistance (Typical, Note 5)	$\theta_{JA}$ ( $^{\circ}C/W$ )
PDIP Package .....	90
SOIC Package .....	175
Maximum Junction Temperature (Plastic Package) .....	$150^{\circ}C$
Maximum Storage Temperature Range .....	$-65^{\circ}C$ to $150^{\circ}C$
Maximum Lead Temperature (Soldering 10s) .....	$300^{\circ}C$

## Operating Conditions

Temperature Range, $T_A$ .....	$-55^{\circ}C$ to $125^{\circ}C$
Supply Voltage Range, $V_{CC}$ (Note 4)	
AC Types .....	1.5V to 5.5V
ACT Types .....	4.5V to 5.5V
DC Input or Output Voltage, $V_I$ , $V_O$ .....	0V to $V_{CC}$
Input Rise and Fall Slew Rate, dt/dv	
AC Types, 1.5V to 3V .....	50ns (Max)
AC Types, 3.6V to 5.5V .....	20ns (Max)
ACT Types, 4.5V to 5.5V .....	10ns (Max)

*CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.*

### NOTES:

3. For up to 4 outputs per device, add  $\pm 25mA$  for each additional output.
4. Unless otherwise specified, all voltages are referenced to ground.
5.  $\theta_{JA}$  is measured with the component mounted on an evaluation PC board in free air.

## DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		$V_{CC}$ (V)	25 $^{\circ}C$		-40 $^{\circ}C$ TO 85 $^{\circ}C$		-55 $^{\circ}C$ TO 125 $^{\circ}C$		UNITS	
		$V_I$ (V)	$I_O$ (mA)		MIN	MAX	MIN	MAX	MIN	MAX		
<b>AC TYPES</b>												
High Level Input Voltage	$V_{IH}$	-	-	1.5	1.2	-	1.2	-	1.2	-	V	
				3	2.1	-	2.1	-	2.1	-	V	
				5.5	3.85	-	3.85	-	3.85	-	V	
Low Level Input Voltage	$V_{IL}$	-	-	1.5	-	0.3	-	0.3	-	0.3	V	
				3	-	0.9	-	0.9	-	0.9	V	
				5.5	-	1.65	-	1.65	-	1.65	V	
High Level Output Voltage	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-0.05	-0.05	1.5	1.4	-	1.4	-	1.4	-	V
			-0.05	-0.05	3	2.9	-	2.9	-	2.9	-	V
			-0.05	-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-4	-4	3	2.58	-	2.48	-	2.4	-	V
			-24	-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75 (Note 6, 7)	-75	5.5	-	-	3.85	-	-	-	V
-50 (Note 6, 7)	-50	5.5	-	-	-	-	3.85	-	V			

**CD54/74AC08, CD54/74ACT08**

**DC Electrical Specifications (Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C		-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	MAX	MIN	MAX	MIN	MAX	
Low Level Output Voltage	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.05	1.5	-	0.1	-	0.1	-	0.1	V
			0.05	3	-	0.1	-	0.1	-	0.1	V
			0.05	4.5	-	0.1	-	0.1	-	0.1	V
			12	3	-	0.36	-	0.44	-	0.5	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> or GND	-	5.5	-	±0.1	-	±1	-	±1	µA
Quiescent Supply Current, SSI	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	4	-	40	-	80	µA
<b>ACT TYPES</b>											
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5 to 5.5	2	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75	5.5	-	-	3.85	-	-	-	V
			-50	5.5	-	-	-	-	3.85	-	V
Low Level Output Voltage	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.05	4.5	-	0.1	-	0.1	-	0.1	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> or GND	-	5.5	-	±0.1	-	±1	-	±1	µA
Quiescent Supply Current, SSI	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	4	-	40	-	80	µA
Additional Supply Current per Input Pin TTL Inputs High 1 Unit Load	ΔI <sub>CC</sub>	V <sub>CC</sub> -2.1	-	4.5 to 5.5	-	2.4	-	2.8	-	3	mA

**NOTES:**

- Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.
- Test verifies a minimum 50Ω transmission-line-drive capability at 85°C, 75Ω at 125°C.

**ACT Input Load Table**

INPUT	UNIT LOAD
All	0.3

NOTE: Unit load is ΔI<sub>CC</sub> limit specified in DC Electrical Specifications Table, e.g., 2.4mA max at 25°C.

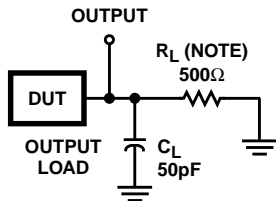
## CD54/74AC08, CD54/74ACT08

### Switching Specifications Input $t_r$ , $t_f = 3\text{ns}$ , $C_L = 50\text{pF}$ (Worst Case)

PARAMETER	SYMBOL	$V_{CC}$ (V)	-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	
<b>AC TYPES</b>									
Propagation Delay, Input to Output	$t_{PLH}$ , $t_{PHL}$	1.5	-	-	99	-	-	109	ns
		3.3 (Note 9)	3.1	-	11.1	3.1	-	12.2	ns
		5 (Note 10)	2.2	-	7.9	2.2	-	8.7	ns
Input Capacitance	$C_I$	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	$C_{PD}$ (Note 11)	-	-	50	-	-	50	-	pF
<b>ACT TYPES</b>									
Propagation Delay, Input to Output	$t_{PLH}$ , $t_{PHL}$	5 (Note 10)	3.3	-	11.7	3.2	-	12.9	ns
Input Capacitance	$C_I$	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	$C_{PD}$ (Note 11)	-	-	50	-	-	50	-	pF

**NOTES:**

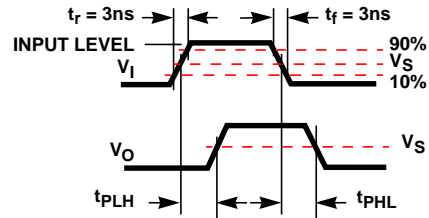
8. Limits tested at 100%.
9. 3.3V Min at 3.6V, Max at 3V.
10. 5V Min at 5.5V, Max at 4.5V.
11.  $C_{PD}$  is used to determine the dynamic power consumption per gate.  
 AC:  $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$   
 ACT:  $P_D = V_{CC}^2 f_i (C_{PD} + C_L) + V_{CC} \Delta I_{CC}$  where  $f_i$  = input frequency,  $C_L$  = output load capacitance,  $V_{CC}$  = supply voltage.



NOTE: For AC Series Only: When  $V_{CC} = 1.5\text{V}$ ,  $R_L = 1\text{k}\Omega$ .

	AC	ACT
Input Level	$V_{CC}$	3V
Input Switching Voltage, $V_S$	$0.5 V_{CC}$	1.5V
Output Switching Voltage, $V_S$	$0.5 V_{CC}$	$0.5 V_{CC}$

**FIGURE 1. PROPAGATION DELAY TIMES**



**FIGURE 2.**

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